

PRODUCT SPECIFICATION

1.44” TN TFT LCD MODULE
MODEL: YDP LCD TN 6 S 144



- < ◇ > Preliminary Specification
- < ◆ > Finally Specification

CUSTOMER’S APPROVAL	
CUSTOMER :	
SIGNATURE:	DATE:

APPROVED BY	PM REVIEWED	PD REVIEWED	PREPARED BY
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Revision History

Revision	Date	Originator	Detail	Remarks
1.0	2023.07.13	LQ	Initial Release	

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	1.44"	
LCD type	TN TFT	
Display Mode	Transmissive /Normally white	
Resolution	128 RGB x 128	Pixels
View Direction	6 O'clock	Best Image
Gray Scale Inversion Direction	12 O'clock	
Module Outline	30.7 (H) x 36.0 (V) x 2.7(T) (Note1)	mm
Active Area	25.4976 (H) x 26.496 (V)	mm
Pixel Size	199.2(H) x 207 (V)	um
Pixel Arrangement	RGB Stripe	
Display Colors	262K	
Interface	8080 8 bit-MCU Interface; Serial Interface(3-line).	
Driver IC	ST7735S	-
With or without touch panel	Without	
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	(6)	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

V_{SS}=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VDD	-0.3	4.8	V
Supply Voltage(Logic)	VDDIO	-0.3	4.8	V
Storage temperature	T _{stg}	-30	+80	°C
Operating temperature	T _{op}	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	VDD	2.5	2.8	4.8	V
	VDDIO	1.65	1.8	3.7	V
Logic Low input voltage	V _{IL}	0	-	0.3*VDDIO	V
Logic High input voltage	V _{IH}	0.7*VDDIO	-	VDDIO	V
Logic Low output voltage	V _{OL}	GND	-	0.2*VDDIO	V
Logic High output voltage	V _{OH}	0.8*VDDIO	-	VDDIO	V
Current Consumption All black	I _{DD} + I _{IO}	-	(2)	-	mA

5. Backlight Characteristic

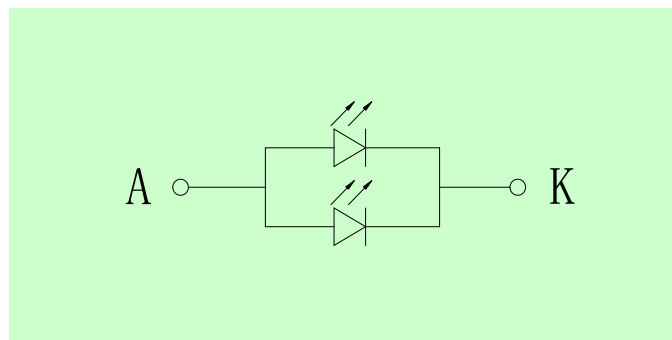
5.1. Backlight Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	T _a =25 °C, I _F =20mA/LED	2.8	3.2	3.4	V
Forward Current	I _F	T _a =25 °C, V _F =3.2V/LED	-	40	-	mA
Power dissipation	P _d	-	-	128	-	mW
Uniformity	Avg	-	-	80	-	%
LED working life(25°C)	-	-	-	30000	-	Hrs
Drive method	Constant current					
LED Configuration	2 White LEDS in parallel					

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at T_a=25 ± 2 °C, 60%RH ± 5%, I_F=20mA/LED.

5.2. Backlighting circuit



6. Optical Characteristics

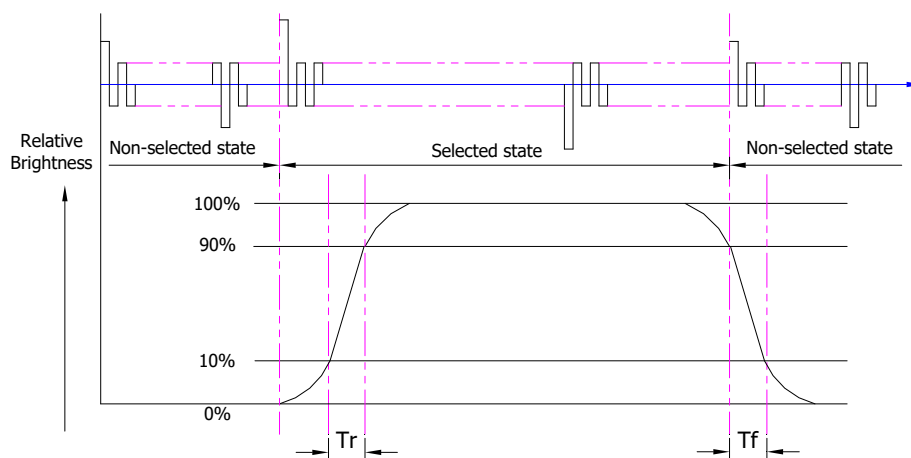
6.1. Optical Characteristics

Ta=25°C, $V_{DD}=2.8V$

Backlight On (Transmissive Mode)	Item		Symbol	Condition	Specification			Unit
					Min.	Typ.	Max.	
	Luminance on TFT(I_f =20mA/LED)		Lv	Normally viewing angle $\theta_x = \varphi_y =0^\circ$	430	540	-	cd/m ²
	Contrast ratio(See 6.3)		CR		400	600	-	
	Response time (See 6.2)		Tr+Tf		-	-	32	ms
	Chromaticity Transmissive (See 6.5)	Red	Xr		-	TBD	-	
			Yr		-	TBD	-	
		Green	Xg		-	TBD	-	
			Yg		-	TBD	-	
		Blue	Xb		-	TBD	-	
			Yb		-	TBD	-	
		White	Xw		-	TBD	-	
			Yw		-	TBD	-	
	Viewing Angle (See 6.4)	Horizontal	θ_{x+}	Center CR≥10	60	-	-	Deg.
			θ_{x-}		60	-	-	
		Vertical	φ_{y+}		60	-	-	
φ_{y-}			60		-	-		
NTSC Ratio(Gamut)				45	50	-	%	

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)



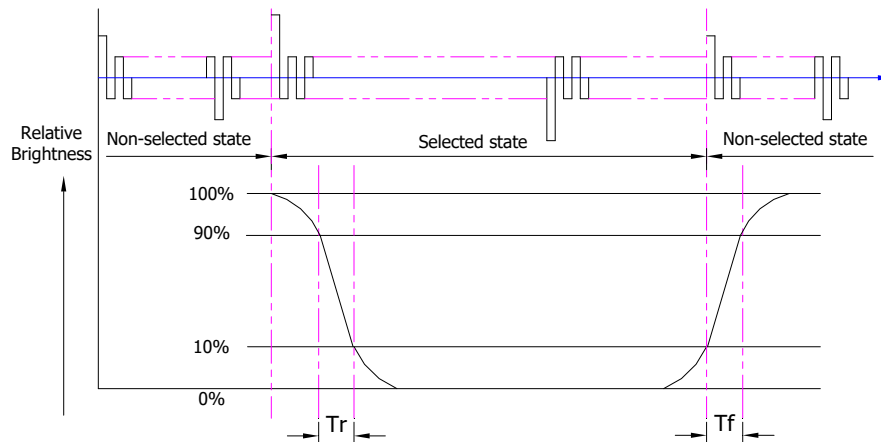
T_r is the time it takes to change from non-selected state with relative luminance 10% to selected state with relative luminance 90%;

T_f is the time it takes to change from selected state with relative luminance 90% to

non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change from non-selected state with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

6.3. Definition of Contrast Ratio

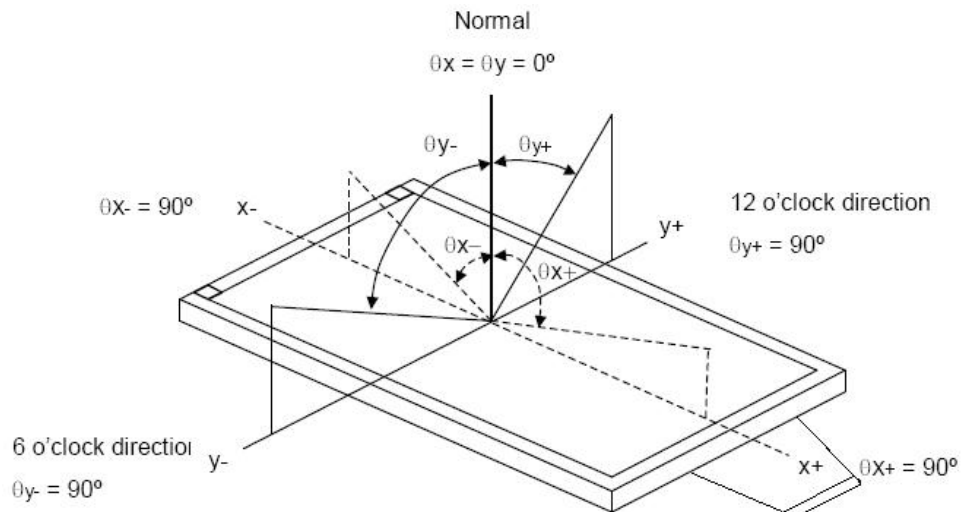
Contrast is measured perpendicular to display surface in reflective and transmissive mode.

The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test pattern	A: All Pixels white
	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R, G, B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

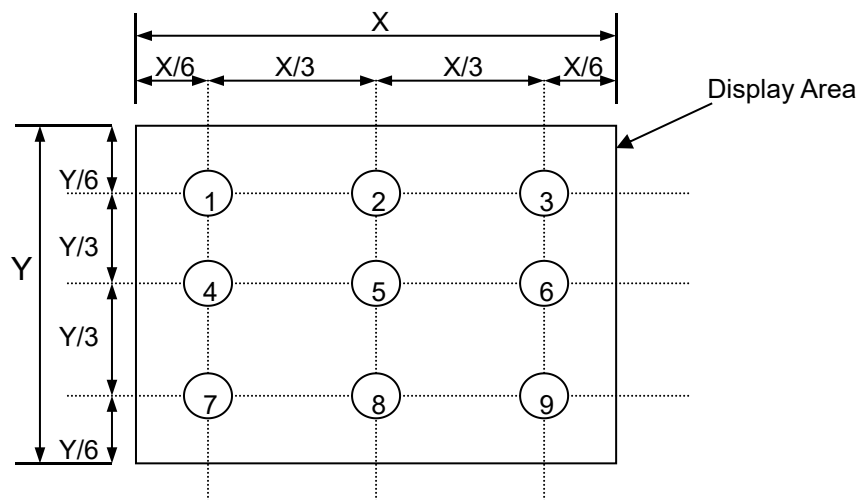
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.6.1. Surface Luminance: $L_V = \text{average } (L_{P1}:L_{P9})$

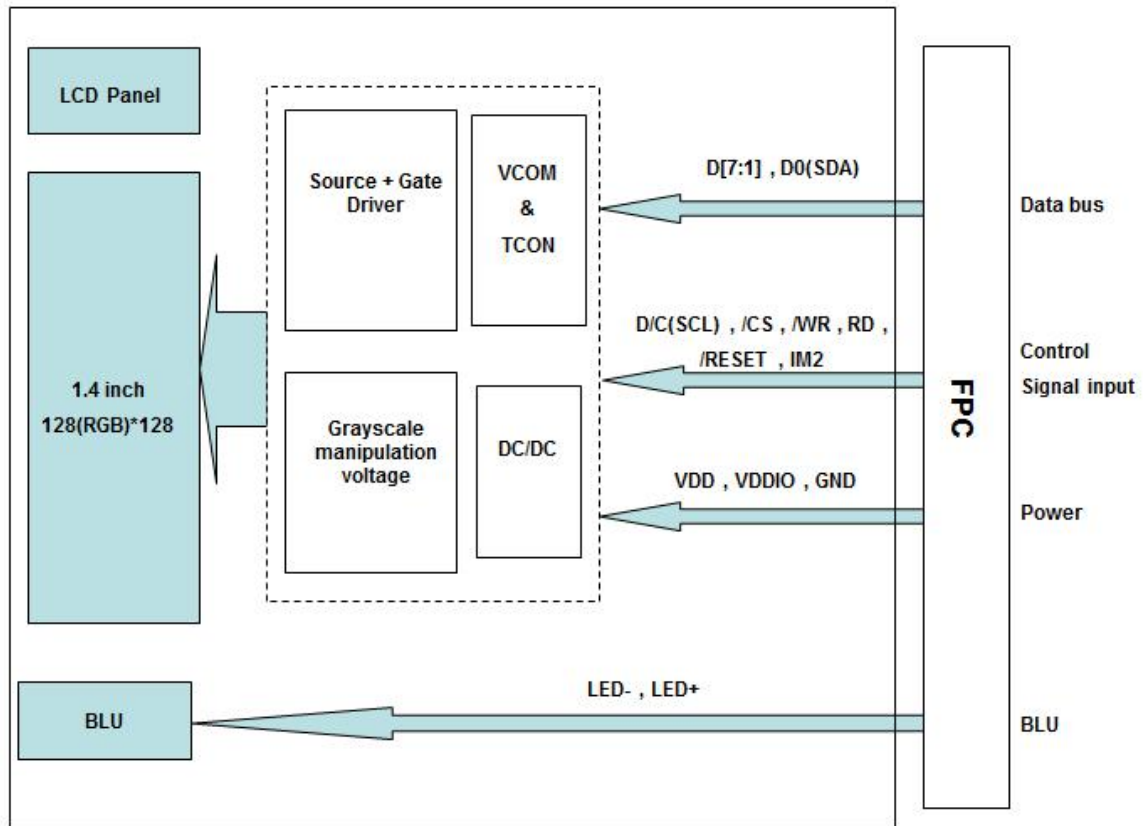
6.6.2. Uniformity = Minimal ($L_{P1}:L_{P9}$) / Maximal ($L_{P1}:L_{P9}$) * 100%

6.6.3. Transmittance = $L_V \text{ on LCD} / L_V \text{ on Backlight} * 100\%$

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply

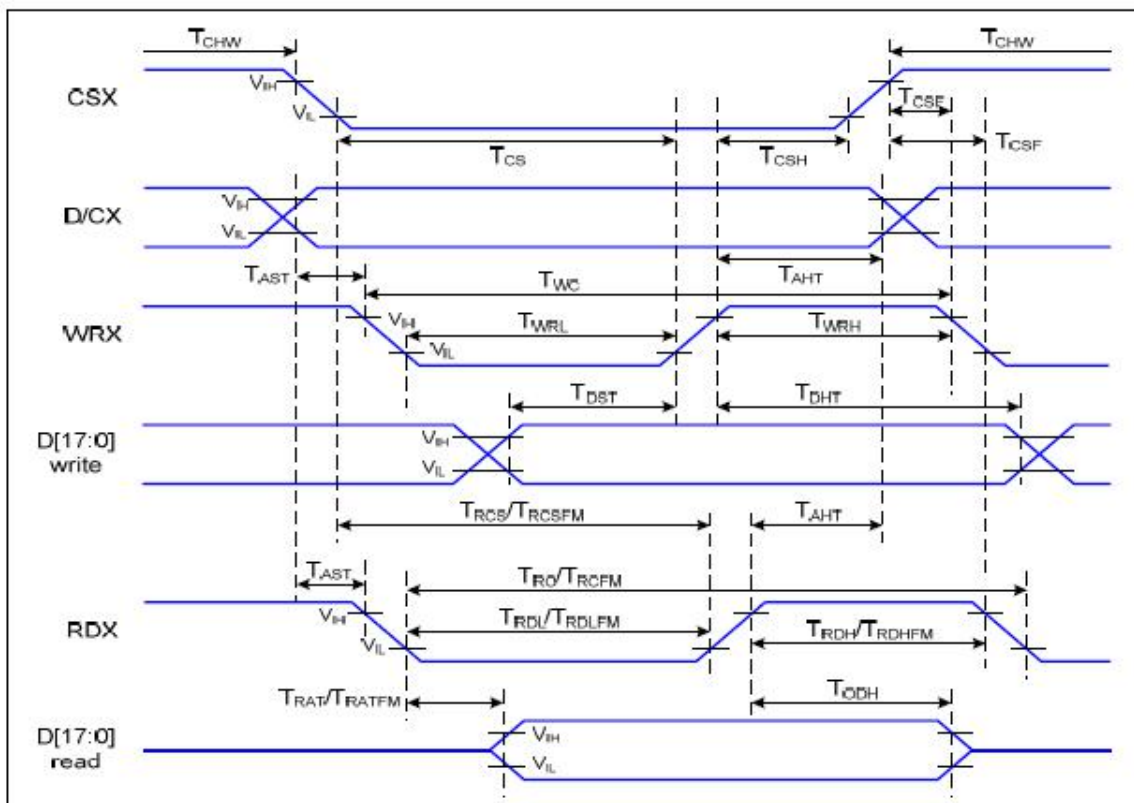


8. Interface Pins Definition

No.	Symbol	Function	Remark
1	GND	Ground	
2	LED-	LED power cathode	
3	LED+	LED power anode	
4	VDDIO	Power Supply for I/O system.	
5	VDD	Power Supply for Analog, Digital System and Booster Circuit.	
6	D/C(SCL)	Display data/command Selection Pin in MCU Interface. D/C='1': Display Data or Parameter. D/C='0': Command Data. In Serial Interface, this is used as SCL.	
7	/CS	Chip select input pin	
8	/WR	Write Enable in MCU Parallel Interface In 4-line SPI, this pin is used as data/ command selection pin.	
9	/RD	Read Enable in 8080 MCU Parallel Interface. If not used, please fix this pin at VDDI or DGND level.	
10	GND	Ground	
11	D7	MCU parallel interface data bus.	
12	D6	MCU parallel interface data bus.	
13	D5	MCU parallel interface data bus.	
14	D4	MCU parallel interface data bus.	
15	D3	MCU parallel interface data bus.	
16	D2	MCU parallel interface data bus.	
17	D1	MCU parallel interface data bus.	
18	D0(SDA)	D0 are used as MCU parallel interface data bus. D0 is the serial input/output signal in serial interface mode	
19	GND	Ground	
20	/RESET	Reset Signal	
21	GND	Ground	
22	IM2	MCU Parallel Interface Bus and Serial Interface select IM2='1', Parallel Interface IM2='0', Serial Interface	

9. AC Characteristics

9.1. Parallel Interface Characteristics: 8-bit Bus (8080 Series MCU Interface)



Ta=25 °C, VDDI=1.65~3.7V, VDD=2.5~4.8V

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	TAST	Address Setup Ttime	0		ns	-
	TAHT	Address Hold Time (Write/Read)	10		ns	
CSX	TCHW	Chip Select "H" Pulse Width	0		ns	-
	TCS	Chip Select Setup Time (Write)	15		ns	
	TRCS	Chip Select Setup Time (Read ID)	45		ns	
	TRCSFM	Chip Select Setup time (Read FM)	355		ns	
	TCSF	Chip Select Wait Time (Write/Read)	10		ns	
	TCSH	Chip Select Hold Time	10		ns	
WRX	TWC	Write Cycle	66		ns	
	TWRH	Control Pulse "H" Duration	15		ns	
	TWRL	Control Pulse "L" Duration	15		ns	
RDX (ID)	TRC	Read Cycle (ID)	160		ns	When Read ID Data
	TRDH	Control Pulse "H" Duration (ID)	90		ns	
	TRDL	Control Pulse "L" Duration (ID)	45		ns	

RDX (FM)	TRCFM	Read Cycle (FM)	450		ns	When Read from Frame Memory
	TRDHFM	Control Pulse "H" Duration (FM)	90		ns	
	TRDLFM	Control Pulse "L" Duration (FM)	355		ns	
D[17:0]	TDST	Data Setup Time	10		ns	For CL=30pF
	TDHT	Data Hold Time	10		ns	
	TRAT	Read Access Time (ID)		40	ns	
	TRATFM	Read Access Time (FM)		340	ns	
	TODH	Output Disable Time	20	80	ns	

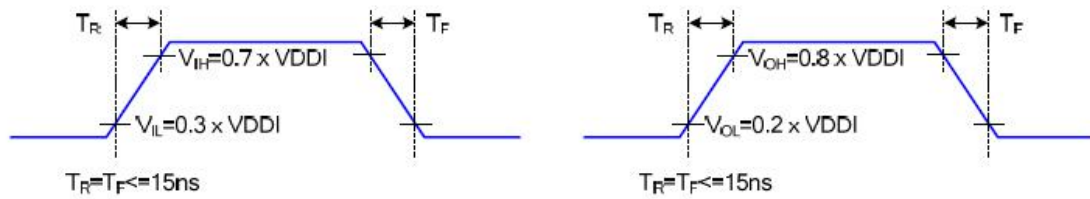


Figure 2 Rising And Falling Timing for Input And Output Signal

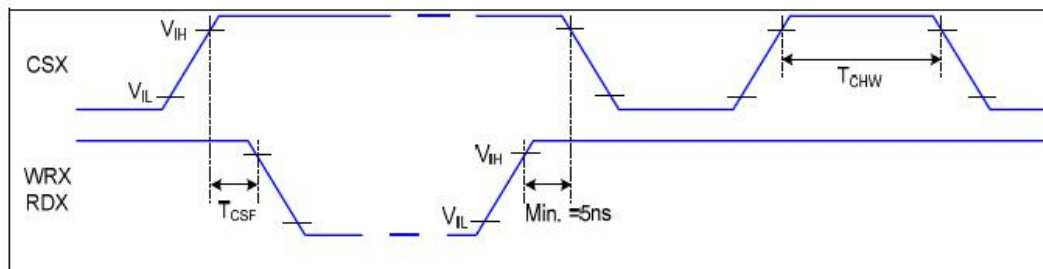


Figure 3 Chip Selection (CSX) Timing

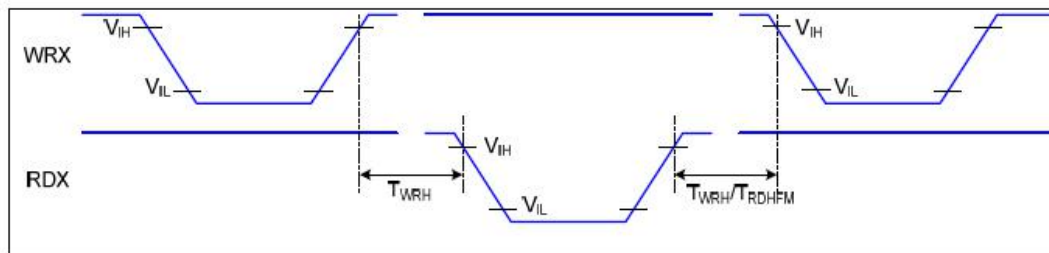
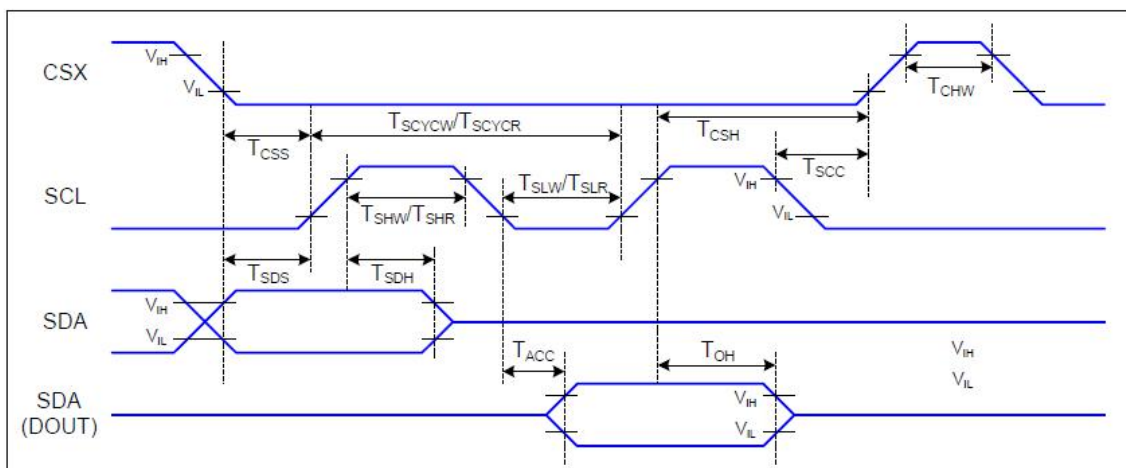


Figure 4 Write-to-Read And Read-to-Write Timing

9.2. Serial Interface Characteristics (3-line Serial)



$T_a=25\text{ }^{\circ}\text{C}$, $V_{DDI}=1.65\sim 3.7\text{V}$, $V_{DD}=2.5\sim 4.8\text{V}$

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	TCSS	Chip Select Setup Time (Write)	15		ns	
	TCSH	Chip Select Hold Time (Write)	15		ns	
	TCSS	Chip Select Setup Time (Read)	60		ns	
	TSCC	Chip Select Hold Time (Read)	65		ns	
	TCHW	Chip Select "H" pulse width	40		ns	
SCL	TSCYCW	Serial Clock Cycle (Write)	66		ns	
	TSHW	SCL "H" Pulse Width (Write)	15		ns	
	TSLW	SCL "L" Pulse Width (Write)	15		ns	
	TSCYCR	Serial Clock Cycle (Read)	150		ns	
	TSHR	SCL "H" Pulse Width (Read)	60		ns	
	TSLR	SCL "L" Pulse Width (Read)	60		ns	
SDA (DIN) (DOUT)	TSDS	Data Setup Time	10		ns	For Maximum $CL=30\text{pF}$ For Minimum $CL=8\text{pF}$
	TSDH	Data Hold Time	10		ns	
	TACC	Access Time	10	50	ns	
	TOH	Output Disable Time	15	50	ns	

10. Quality Assurance

10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2.Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3.Nonconforming Analysis & Disposition

10.3.1. Nonconforming analysis:

10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.

10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.

10.3.2. Disposition of nonconforming:

10.3.2.1. Non-conforming product over PPM level will be replaced.

10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

10.4.Agreement Items

Shall negotiate with customer if the following situation occurs:

10.4.1. There is any discrepancy in standard of quality assurance.

10.4.2. Additional requirement to be added in product specification.

10.4.3. Any other special problem.

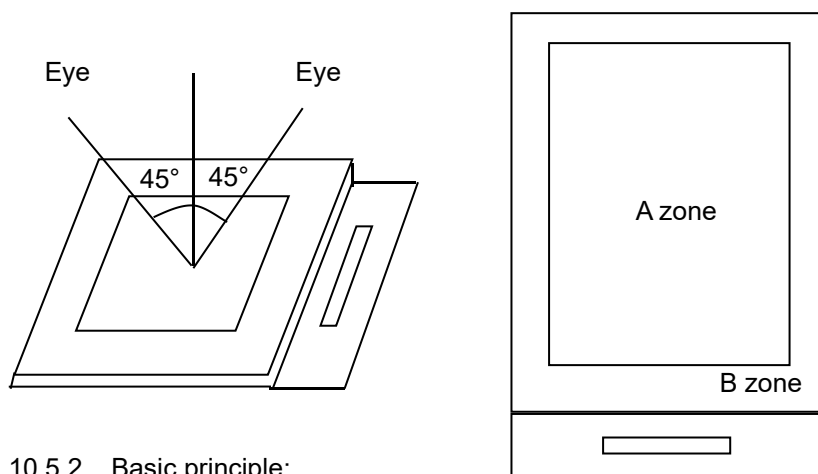
10.5. Standard of the Product Visual Inspection

10.5.1. Appearance inspection:

10.5.1.1. The inspection must be under illumination about 1000 – 1500 lx, and the distance of view must be at 30cm ± 2cm.

10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,

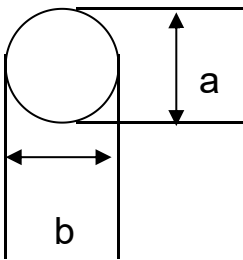


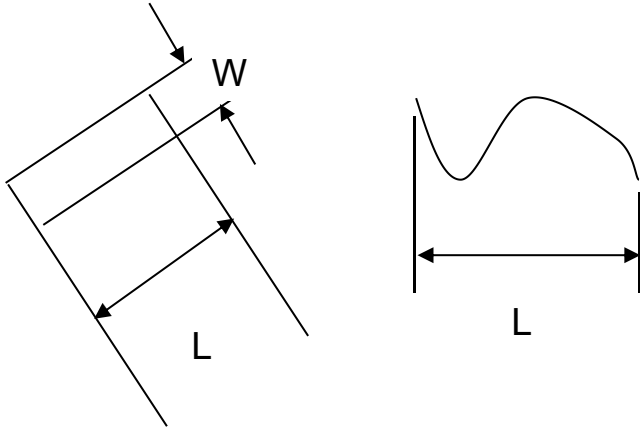
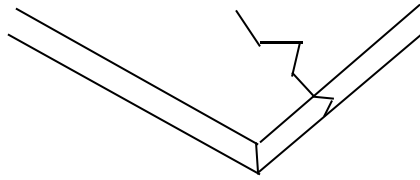
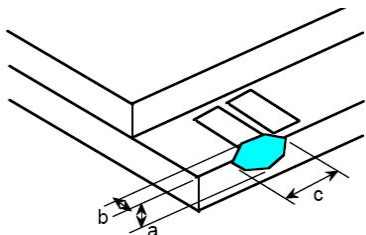
10.5.2. Basic principle:

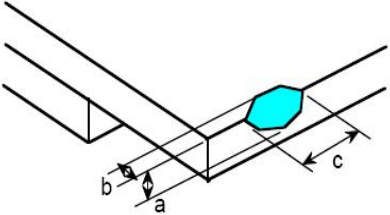
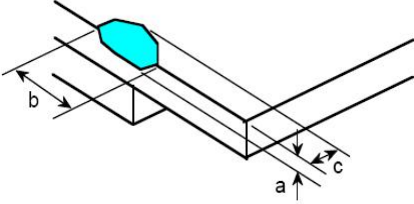
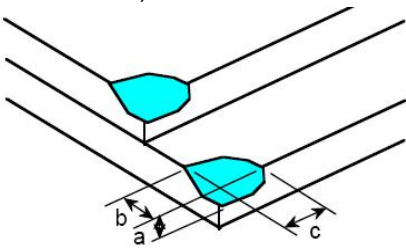
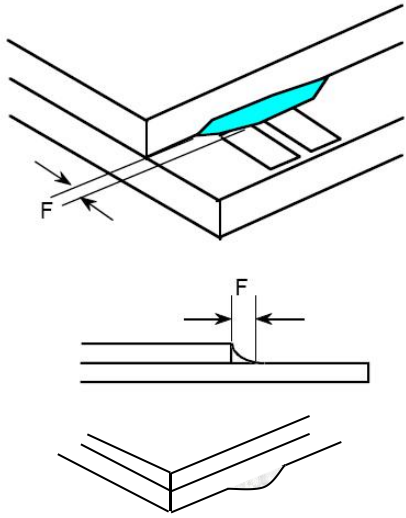
10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

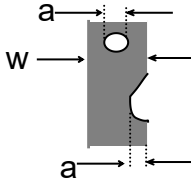
10.5.2.2. New item must be added on time when it is necessary.

10.6. Inspection Specification

No.	Item	Criteria (Unit: mm)																		
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	 $\varphi = (a + b) / 2$	<table><tr><th>Size \ Area</th><th>Acc. Qty</th></tr><tr><td>$\varphi \leq 0.10$</td><td>Ignore</td></tr><tr><td>$0.10 < \varphi \leq 0.15$</td><td>2</td></tr><tr><td>$0.15 < \varphi \leq 0.25$</td><td>1</td></tr><tr><td>$0.25 < \varphi$</td><td>0</td></tr><tr><td>Total</td><td>2 no include $\varphi \leq 0.10$</td></tr></table>	Size \ Area	Acc. Qty	$\varphi \leq 0.10$	Ignore	$0.10 < \varphi \leq 0.15$	2	$0.15 < \varphi \leq 0.25$	1	$0.25 < \varphi$	0	Total	2 no include $\varphi \leq 0.10$					
		Size \ Area	Acc. Qty																	
$\varphi \leq 0.10$	Ignore																			
$0.10 < \varphi \leq 0.15$	2																			
$0.15 < \varphi \leq 0.25$	1																			
$0.25 < \varphi$	0																			
Total	2 no include $\varphi \leq 0.10$																			
		Distance between 2 defects should more than 3mm apart.																		
02	Electrical Defect (Minor defect)	<table><tr><td></td><td>Display Area</td><td>Total</td><td rowspan="4">Note1</td></tr><tr><td>Bright dot</td><td>0</td><td>0</td></tr><tr><td>Dark dot</td><td>$N \leq 2$</td><td>$N \leq 2$</td></tr><tr><td>Total dot</td><td>$N \leq 2$</td><td>$N \leq 2$</td></tr><tr><td>Mura</td><td colspan="2">Not visible through 5% ND filter.</td><td>Note 2</td></tr></table>		Display Area	Total	Note1	Bright dot	0	0	Dark dot	$N \leq 2$	$N \leq 2$	Total dot	$N \leq 2$	$N \leq 2$	Mura	Not visible through 5% ND filter.		Note 2	
			Display Area	Total	Note1															
Bright dot	0	0																		
Dark dot	$N \leq 2$	$N \leq 2$																		
Total dot	$N \leq 2$	$N \leq 2$																		
Mura	Not visible through 5% ND filter.		Note 2																	
		Remark: 1. Bright dot caused by scratch and foreign object accords to item 1.																		

03	Black and White line Scratch Foreign material (Line type) (Minor defect)	 <table><tr><th>Length</th><th>Width</th><th>Acc. Qty</th></tr><tr><td>/</td><td>$W \leq 0.03$</td><td>gnore</td></tr><tr><td>$L \leq 2.5$</td><td>$0.03 < W \leq 0.05$</td><td>3</td></tr><tr><td>$L \leq 2.5$</td><td>$0.05 < W \leq 0.10$</td><td>2</td></tr><tr><td>/</td><td>$0.1 < W$</td><td>0</td></tr><tr><td colspan="2">Total</td><td>3</td></tr></table> Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.	Length	Width	Acc. Qty	/	$W \leq 0.03$	gnore	$L \leq 2.5$	$0.03 < W \leq 0.05$	3	$L \leq 2.5$	$0.05 < W \leq 0.10$	2	/	$0.1 < W$	0	Total		3
Length	Width	Acc. Qty																		
/	$W \leq 0.03$	gnore																		
$L \leq 2.5$	$0.03 < W \leq 0.05$	3																		
$L \leq 2.5$	$0.05 < W \leq 0.10$	2																		
/	$0.1 < W$	0																		
Total		3																		
04	Glass Crack (Minor defect)	 Crack is potential to enlarge, any type is not allowed.																		
05	Glass Chipping Pad Area: (Minor defect)	 <table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>3</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	3	$a < \text{Glass Thickness}$											
Length and Width	Acc. Qty																			
$c > 3.0, b < 1.0$	1																			
$c < 3.0, b < 1.0$	3																			
$a < \text{Glass Thickness}$																				

06	Glass Chipping Rear of Pad Area: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
07	Glass Chipping Except Pad Area: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
08	Glass Corner Chipping: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c < 3.0, b < 3.0$</td><td>Ignore</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c < 3.0, b < 3.0$	Ignore	$a < \text{Glass Thickness}$					
Length and Width	Acc. Qty											
$c < 3.0, b < 3.0$	Ignore											
$a < \text{Glass Thickness}$												
09	Glass Burr: (Minor defect) 	<table><tr><th>Length</th><th>Acc. Qty</th></tr><tr><td>$F < 1.0$</td><td>Ignore</td></tr></table> Glass burr don't affect assemble and module dimension.	Length	Acc. Qty	$F < 1.0$	Ignore						
Length	Acc. Qty											
$F < 1.0$	Ignore											

10	FPC Defect: (Minor defect) 	10.1 Dent, pinhole width $a < w/3$. (w: circuitry width.) 10.2 Open circuit is unacceptable. 10.3 No oxidation, contamination and distortion.										
11	Bubble on Polarizer (Minor defect)	<table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$\varphi \leq 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < \varphi \leq 0.30$</td><td>4</td></tr><tr><td>$0.30 < \varphi \leq 0.50$</td><td>1</td></tr><tr><td>$0.50 < \varphi$</td><td>None</td></tr></table>	Diameter	Acc. Qty	$\varphi \leq 0.20$	Ignore	$0.20 < \varphi \leq 0.30$	4	$0.30 < \varphi \leq 0.50$	1	$0.50 < \varphi$	None
Diameter	Acc. Qty											
$\varphi \leq 0.20$	Ignore											
$0.20 < \varphi \leq 0.30$	4											
$0.30 < \varphi \leq 0.50$	1											
$0.50 < \varphi$	None											
12	Dent on Polarizer (Minor defect)	<table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$\varphi \leq 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < \varphi \leq 0.30$</td><td>4</td></tr><tr><td>$0.30 < \varphi \leq 0.50$</td><td>1</td></tr><tr><td>$0.50 < \varphi$</td><td>None</td></tr></table>	Diameter	Acc. Qty	$\varphi \leq 0.20$	Ignore	$0.20 < \varphi \leq 0.30$	4	$0.30 < \varphi \leq 0.50$	1	$0.50 < \varphi$	None
Diameter	Acc. Qty											
$\varphi \leq 0.20$	Ignore											
$0.20 < \varphi \leq 0.30$	4											
$0.30 < \varphi \leq 0.50$	1											
$0.50 < \varphi$	None											
13	Bezel	13.1 No rust, distortion on the Bezel. 13.2 No visible fingerprints, stains or other contamination.										
14	PCB	14.1 No distortion or contamination on PCB terminals. 14.2 All components on PCB must same as documented on the BOM/component layout. 14.3 Follow IPC-A-600F.										
15	Soldering	Follow IPC-A-610C standard										
16	Electrical Defect (Major defect)	The below defects must be rejected. 16.1 Missing vertical / horizontal segment, 16.2 Abnormal Display. 16.3 No function or no display. 16.4 Current exceeds product specifications. 16.5 LCD viewing angle defect. 16.6 No Backlight. 16.7 Dark Backlight. 16.8 Touch Panel no function.										

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.

10.7.2. Two minor defects are equal to one major in lot sampling inspection.

10.8. Identification/marketing criteria

Any unit with illegible / wrong / double or no marking/ label shall be rejected.

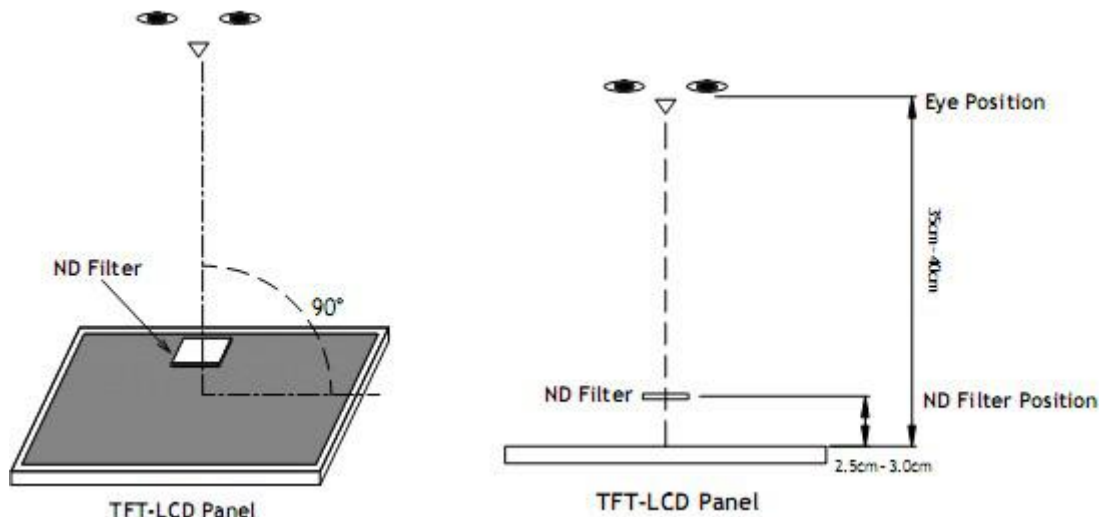
10.9. Packing

10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.

10.9.2. Modules inside package box should have compliant mark.

10.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350\text{mm} \pm 50\text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is $350\text{mm} \pm 50\text{mm}$.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2-2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1-2008
3	High Humidity Storage	50℃, 90%RH, 96Hrs	2	GB/T2423.3-2016
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2-2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1-2008
6	Thermal Cycling Test Storage	-20℃, 60min~70℃, 60min, 20 cycles.	2	GB/T2423.22-2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14-2009
8	Electrical Static Discharge	Air:±8KV 150pF/330Ω 5 times Contact:±4KV 150pF/330Ω 5 times	2	GB/T17626.2-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8-1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

12. Precautions and Warranty

12.1.Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2.Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3.Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

12.4.Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

- 12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

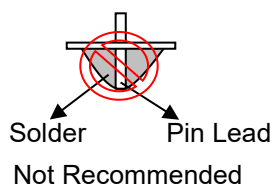
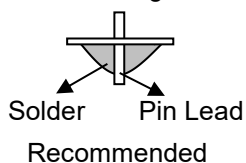
Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting



12.4.2. Pins of EL

- 12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

- 12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

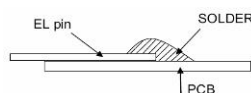
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

- 12.4.2.4. No horizontal press on the EL leads during soldering.

- 12.4.2.5. 180° bend EL leads three times is not allowed.
-

12.4.2.6. Solder Wetting

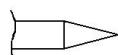


Recommended

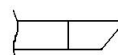


Not Recommended

12.4.2.7. The type of the solder iron:

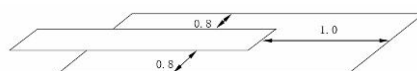


Recommended



Not Recommended

12.4.2.8. Solder Pad



12.5.Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. *Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.*

12.6.Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

12.7.Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Packaging

TBD

14. Outline Drawing

